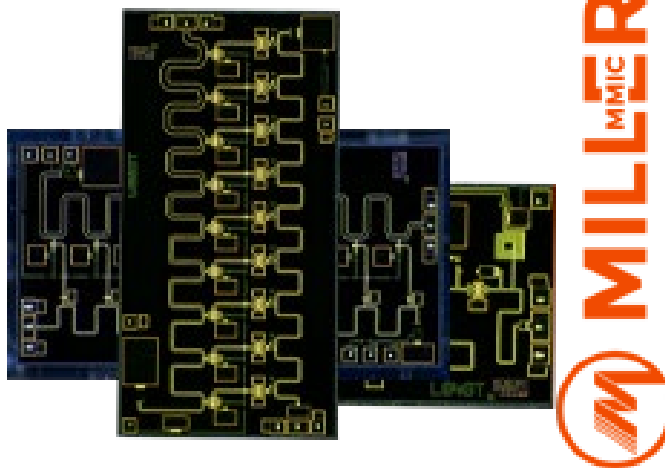


Features

- Ultra broadband three channel attenuator
- Frequency Range: DC - 40GHz
- 3 Channels with 3 different Attenuation value
- Power Handling: 27dBm
- 50Ω Input and Output Impedance
- Return Loss: 20dB
- Bare Die (QFN Available)
- RoHS & REACH Compliant

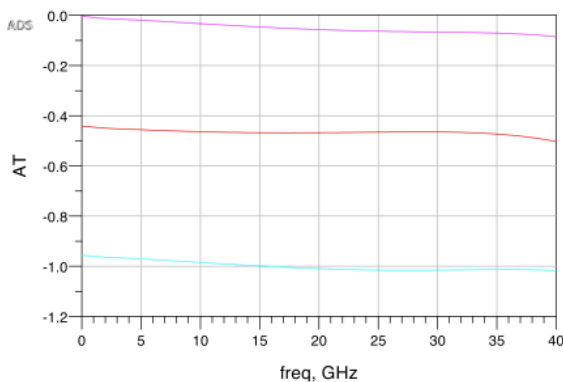


Typical Applications

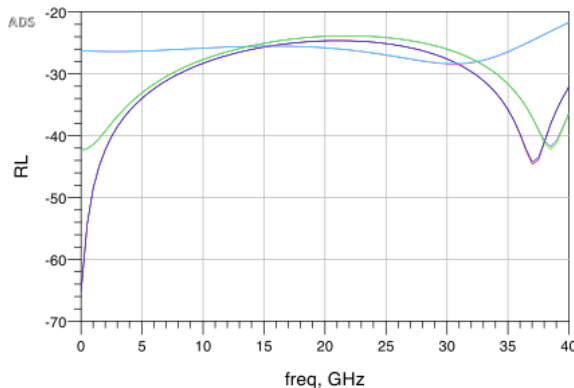
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- General Purpose

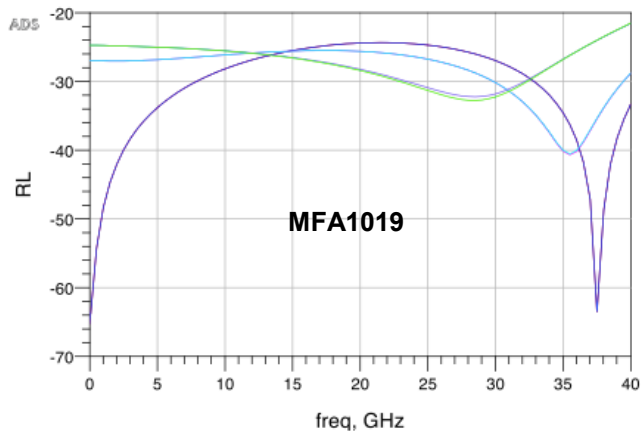
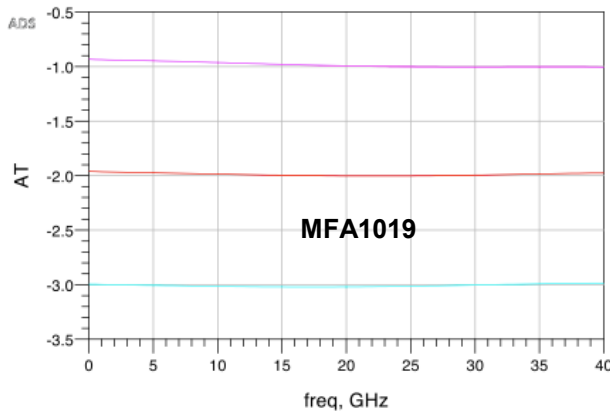
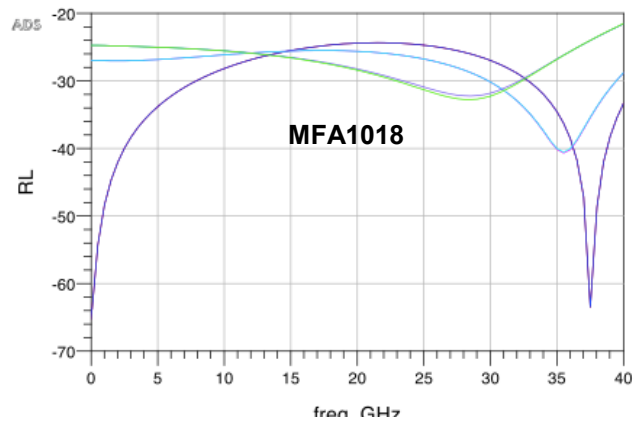
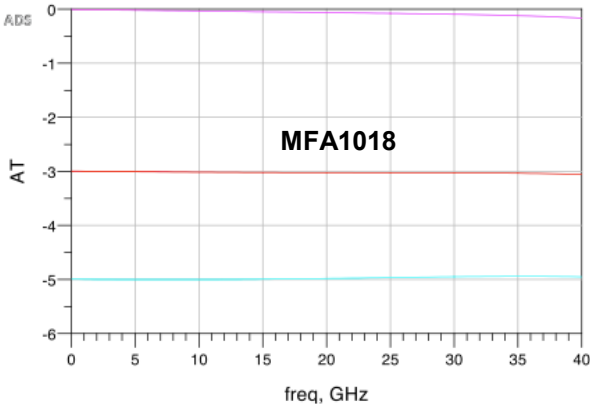
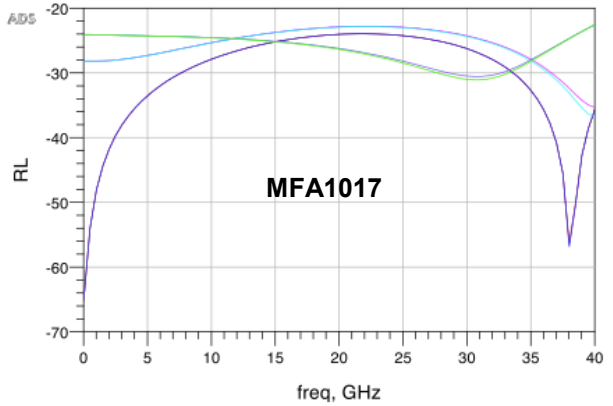
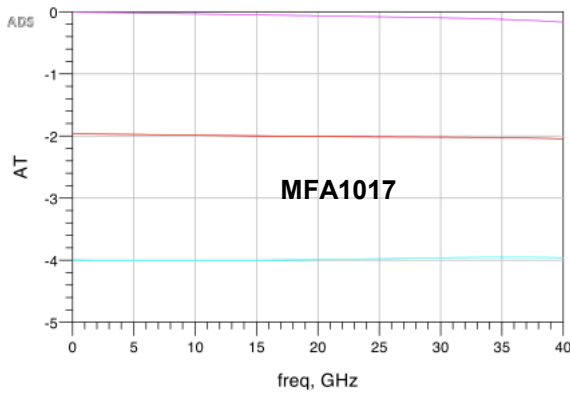
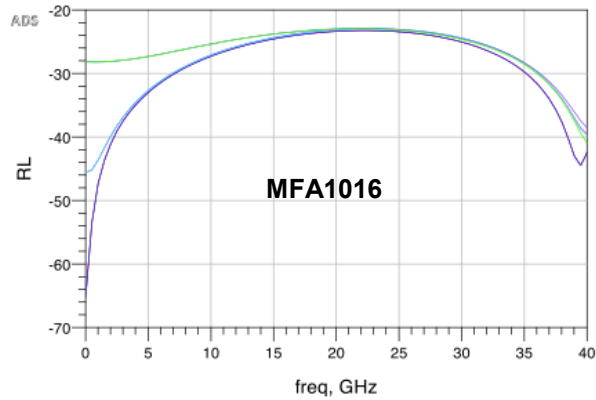
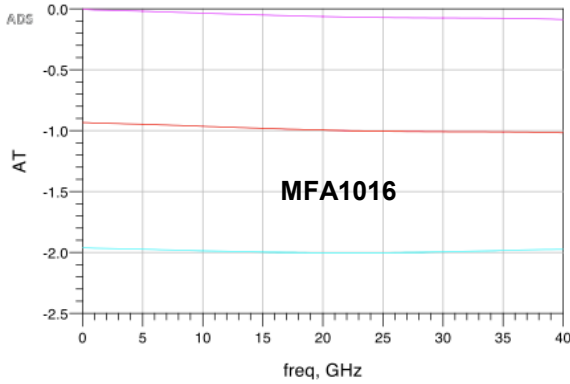
Part Number	Product Description	Frequency (GHz)	Channel	Attenuation (dB)	Power (dBm)	Flatness (dB)	VSWR
MFA1015	3 Channel Fixed Attenuator	DC-40	3	0/0.5/1	27	±0.3	1.22
MFA1016	3 Channel Fixed Attenuator	DC-40	3	0/1/2	27	±0.3	1.22
MFA1017	3 Channel Fixed Attenuator	DC-40	3	0/2/4	27	±0.3	1.22
MFA1018	3 Channel Fixed Attenuator	DC-40	3	0/3/5	27	±0.3	1.22
MFA1019	3 Channel Fixed Attenuator	DC-40	3	1/2/3	27	±0.3	1.22

MFA1015



MFA1015

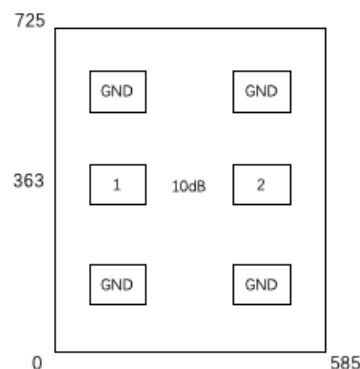




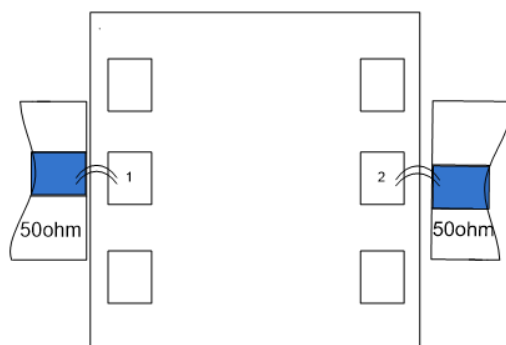
Outline Drawing:

 All Dimensions in μm

Pad	Function	Description
1	RF IN	RF signal input terminal; DC blocking capacitor required.
2	RF OUT	RF signal output terminal; DC blocking capacitor required.
Die bottom	GND	Die bottom must be connected to RF/DC ground.



Assembly Drawing



Notes:

1. Die thickness: $100\mu\text{m}$
2. Typical bond pad is $100*100\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum input power: +27dBm
2. Operating temperature: -55°C to $+85^{\circ}\text{C}$
3. Storage temperature: -65°C to $+150^{\circ}\text{C}$

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